Ignition IGBT 18 Amps, 450 Volts

N-Channel DPAK

This Logic Level Insulated Gate Bipolar Transistor (IGBT) features monolithic circuitry integrating ESD and Over-Voltage clamped protection for use in inductive coil drivers applications. Primary uses include Ignition, Direct Fuel Injection, or wherever high voltage and high current switching is required.

Features

- Ideal for Coil-on-Plug Applications
- DPAK Package Offers Smaller Footprint for Increased Board Space
- Gate-Emitter ESD Protection
- Temperature Compensated Gate-Collector Voltage Clamp Limits Stress Applied to Load
- Low Threshold Voltage Interfaces Power Loads to Logic or Microprocessor Devices
- Low Saturation Voltage
- High Pulsed Current Capability
- Emitter Ballasting for Short-Circuit Capability
- This is a Pb-Free Device

MAXIMUM RATINGS (T.I = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V _{CES}	500	V_{DC}
Collector-Gate Voltage	V _{CER}	500	V_{DC}
Gate-Emitter Voltage	V _{GE}	18	V_{DC}
Collector Current–Continuous @ T _C = 25°C – Pulsed	I _C	18 50	A _{DC} A _{AC}
ESD (Human Body Model) $R = 1500 Ω, C = 100 pF$	ESD	8.0	kV
ESD (Machine Model) R = 0 Ω, C = 200 pF	ESD	400	٧
Total Power Dissipation @ T _C = 25°C Derate above 25°C	P _D	115 0.77	Watts W/°C
Operating and Storage Temperature Range	T _J , T _{stg}	-55 to +175	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1

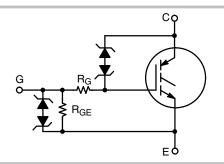


ON Semiconductor®

http://onsemi.com

18 AMPS 450 VOLTS

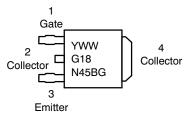
 $V_{CE(on)} \le 2.1 \text{ V } @ I_C = 10 \text{ A}, V_{GE} \ge 4.5 \text{ V}$





DPAK CASE 369C STYLE 7

MARKING DIAGRAM



G18N45B = Device Code
Y = Year
WW = Work Week
G = Pb-Free Device

ORDERING INFORMATION

Device	Package	Shipping [†]
NGD18N45CLBT4G	DPAK (Pb-Free)	2500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

UNCLAMPED COLLECTOR-TO-EMITTER AVALANCHE CHARACTERISTICS (Note 2)

Characteristic	Symbol	Value	Unit			
Single Pulse Collector–to–Emitter Avalanche Energy $V_{CC}=50~\text{V},~V_{GE}=5.0~\text{V},~\text{Pk}~\text{I}_L=26.0~\text{A},~\text{L}=1.0~\text{mH},~\text{Starting}~\text{T}_\text{J}=25^{\circ}\text{C}\\ V_{CC}=50~\text{V},~\text{V}_{GE}=5.0~\text{V},~\text{Pk}~\text{I}_L=10.0~\text{A},~\text{L}=8.4~\text{mH},~\text{Starting}~\text{T}_\text{J}=25^{\circ}\text{C}\\ V_{CC}=50~\text{V},~\text{V}_{GE}=5.0~\text{V},~\text{Pk}~\text{I}_L=15.4~\text{A},~\text{L}=2.0~\text{mH},~\text{Starting}~\text{T}_\text{J}=150^{\circ}\text{C}\\ V_{CC}=50~\text{V},~\text{V}_{GE}=5.0~\text{V},~\text{Pk}~\text{I}_L=5.7~\text{A},~\text{L}=15.2~\text{mH},~\text{Starting}~\text{T}_\text{J}=150^{\circ}\text{C}\\ \end{array}$	E _{AS}	338 420 237 247	mJ			
MAXIMUM SHORT-CIRCUIT TIMES						
Short Circuit Withstand Time – Test 1 (See Figure 17, 3 Pulses with 10 ms Period, T _a = 105°C)	t _{sc1-1}	1000	μS			

Short Circuit Withstand Time – Test 1 (See Figure 17, 3 Pulses with 10 ms Period, T _a = 105°C)	t _{sc1-1}	1000	μS
Short Circuit Withstand Time – Test 1 (See Figure 17, 3 Pulses with 10 ms Period, T _a = 150°C)	t _{sc1-2}	800	μS
Short Circuit Withstand Time – Test 2 (See Figure 18, 3 Pulses with 10 ms Period, T _a = 105°C)	t _{sc2-1}	5	ms
Short Circuit Withstand Time – Test 2	ter2-2	1	ms

(See Figure 18, 3 Pulses with 10 ms Period, T_a = 150°C) THERMAL CHARACTERISTICS

Thermal Resistance, Junction to Case		$R_{ heta JC}$	1.3	°C/W
Thermal Resistance, Junction to Ambient	DPAK (Note 1)	$R_{ heta JA}$	95	°C/W
Maximum Lead Temperature for Soldering Purposes, 1	/8" from case for 5 seconds	T_L	275	°C

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Test Conditions	Temperature	Min	Тур	Max	Unit
OFF CHARACTERISTICS (Note 2)							
Collector-Emitter Clamp Voltage	BV _{CES}	I _C = 2.0 mA	T _J = -40°C to 150°C	430	455	470	V _{DC}
		I _C = 10 mA	T _J = -40°C to 150°C	440	475	500	
Zero Gate Voltage Collector Current	I _{CES}		T _J = 25°C	-	0.5	20	μA _{DC}
		$V_{CE} = 350 \text{ V},$ $V_{GF} = 0 \text{ V}$	T _J = 150°C	-	75	250	
		-GE -	T _J = −40°C	_	0.2	10	
		V _{CE} = 15 V, V _{GE} = 0 V	T _J = 25°C	_	_	2.0	
Reverse Collector-Emitter Leakage Current	I _{ECS}		T _J = 25°C	-	0.7	1.0	mA
		V _{CE} = −24 V	T _J = 150°C	-	12	25	
			T _J = -40°C	_	0.1	1.0	
Reverse Collector-Emitter Clamp Voltage	B _{VCES(R)}		T _J = 25°C	24	27	30	V_{DC}
		$I_C = -75 \text{ mA}$	T _J = 150°C	26	29	33	
			T _J = -40°C	23	26	29	
Gate-Emitter Clamp Voltage	BV _{GES}	I _G = 5.0 mA	$T_J = -40^{\circ}\text{C} \text{ to}$ 150°C	11	13	15	V _{DC}
Gate-Emitter Leakage Current	I _{GES}	V _{GE} = 10 V	T _J = -40°C to 150°C	384	590	700	μA _{DC}
Gate Resistor	R_{G}	-	T _J = -40°C to 150°C	-	70	-	Ω
Gate Emitter Resistor	R _{GE}	-	T _J = -40°C to 150°C	10	16	26	kΩ

^{1.} When surface mounted to an FR4 board using the minimum recommended pad size.

ELECTRICAL CHARACTERISTICS (continued)

Characteristic	Symbol	Test Conditions	Temperature	Min	Тур	Max	Unit
ON CHARACTERISTICS (Note 2)	•	•				•	
Gate Threshold Voltage	V _{GE(th)}		T _J = 25°C	1.1	1.56	1.9	- "
		I _C = 1.0 mA, V _{GE} = V _{CE}	T _J = 150°C	0.75	1.08	1.4	
		VGE - VCE	T _J = -40°C	1.2	1.75	2.1	1
Collector-to-Emitter On-Voltage	V _{CE(on)}	I _C = 7 A, V _{GE} = 4.5 V	T _J = -40°C to 150°C	1.10	1.84	2.30	٧
		I _C = 7 A, V _{GE} = 4.0 V	T _J = -40°C to 150°C	1.15	1.89	2.35	
		I _C = 7 A, V _{GE} = 3.7 V	T _J = -40°C to 150°C	1.20	1.93	2.50	
		I _C = 10 A, V _{GE} = 4.5 V	T _J = -40°C to 150°C	1.45	2.07	2.65	
		I _C = 10 A, V _{GE} = 4.0 V	T _J = -40°C to 150°C	1.50	2.13	2.80	
		I _C = 10 A, V _{GE} = 3.7 V	T _J = -40°C to 150°C	1.55	2.19	2.85	
		I _C = 10 mA, V _{GE} = 4.5 V	T _J = -40°C to 150°C	-	0.65	1.00	
Threshold Temperature Coefficient (Negative)	-	-	-	-	3.5	_	mV/°C
Forward Transconductance	gfs	V _{CE} = 5.0 V, I _C = 6.0 A	T _J = -40°C to 150°C	6.0	14	25	Mhos
YNAMIC CHARACTERISTICS (Note 2)			•				
Input Capacitance	C _{ISS}			400	780	1000	pF
Output Capacitance	C _{OSS}	$V_{CC} = 25 \text{ V}, V_{GE} = 0 \text{ V}$ f = 1.0 MHz	T _J = -40°C to 150°C	50	72	100	
Transfer Capacitance	C _{RSS}	1 = 1.0 Wil i2		4.0	6	10	1
WITCHING CHARACTERISTICS (Note	2)	-	-		-		
Turn-Off Delay Time	t _{d(off)}	$V_{CC} = 300 \text{ V}, V_{GE} = 5 \text{ V}$ $R_G = 1.0 \text{ k}\Omega, R_L = 46 \Omega,$	T _J = 25°C	1.0	2.9	12	μSec
Fall Time	t _f	$V_{CC} = 300 \text{ V}, V_{GE} = 5 \text{ V}$ $R_G = 1.0 \text{ k}\Omega, R_L = 46 \Omega,$	T _J = 25°C	1.0	2.5	7.0	
Turn-On Delay Time	t _{d(on)}	$V_{CC} = 14 \text{ V}, V_{GE} = 5 \text{ V}$ $R_G = 1.0 \text{ k}\Omega, R_L = 1 \Omega$	T _J = 25°C	0.1	0.42	1.4	μSec
Rise Time	t _r	$V_{CC} = 14 \text{ V}, V_{GE} = 5 \text{ V}$ $R_G = 1.0 \text{ k}\Omega, R_L = 1 \Omega$	T _J = 25°C	1.0	2.5	9.0]

^{2.} Electrical Characteristics at temperature other than 25°C, Dynamic and Switching characteristics are not subject to production testing.

TYPICAL ELECTRICAL CHARACTERISTICS (unless otherwise noted)

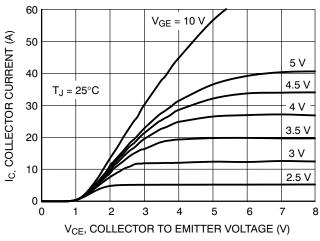


Figure 1. Output Characteristics

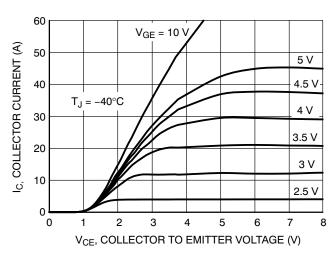


Figure 2. Output Characteristics

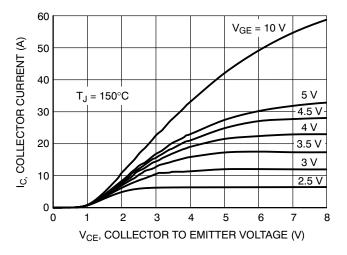


Figure 3. Output Characteristics

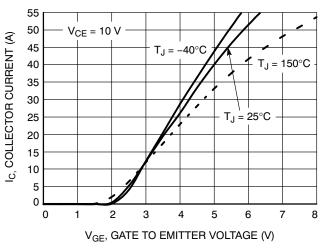


Figure 4. Transfer Characteristics

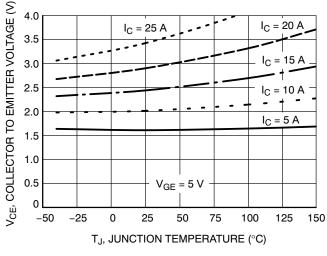


Figure 5. Collector-to-Emitter Saturation Voltage vs. Junction Temperature

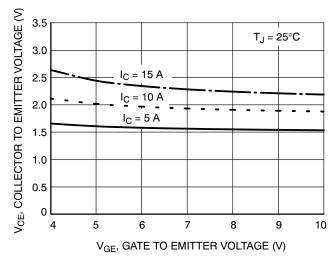


Figure 6. Collector-to-Emitter Voltage vs.
Gate-to-Emitter Voltage

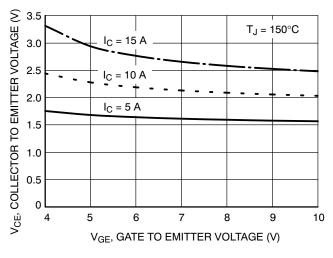


Figure 7. Collector-to-Emitter Voltage vs.

Gate-to-Emitter Voltage

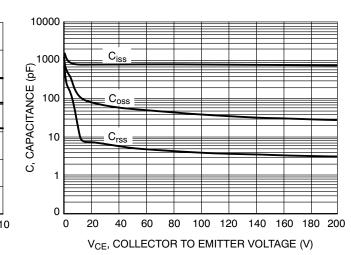


Figure 8. Capacitance Variation

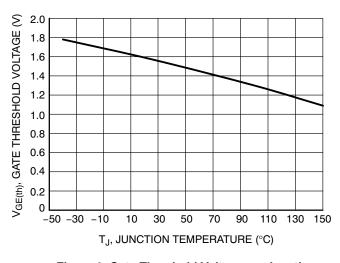


Figure 9. Gate Threshold Voltage vs. Junction Temperature

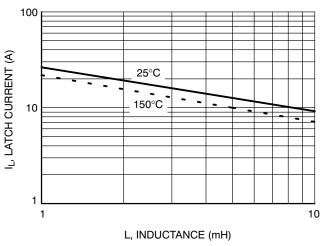


Figure 10. Minimum Open Secondary Latch Current vs. Inductance

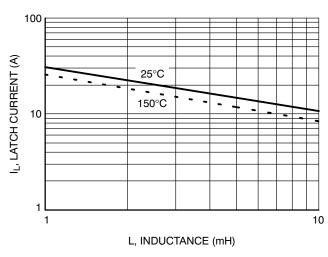


Figure 11. Typical Open Secondary Latch Current vs. Inductance

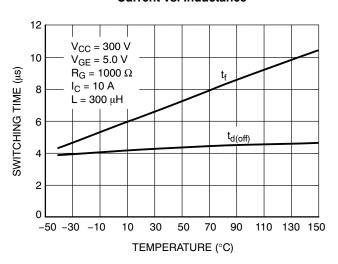


Figure 12. Inductive Switching Fall Time vs.
Temperature

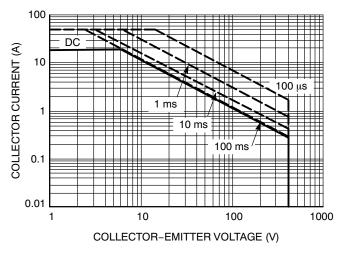


Figure 13. Single Pulse Safe Operating Area (Mounted on an Infinite Heatsink at $T_A = 25$ °C)

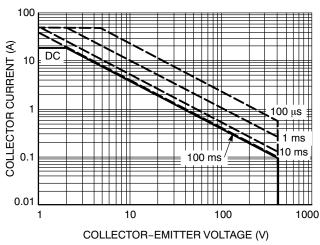


Figure 14. Single Pulse Safe Operating Area (Mounted on an Infinite Heatsink at T_A = 125°C)

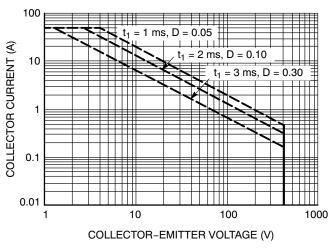


Figure 15. Pulse Train Safe Operating Area (Mounted on an Infinite Heatsink at $T_C = 25^{\circ}C$)

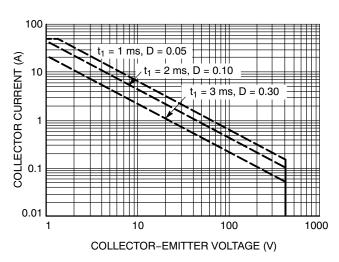


Figure 16. Pulse Train Safe Operating Area (Mounted on an Infinite Heatsink at $T_C = 125^{\circ}C$)

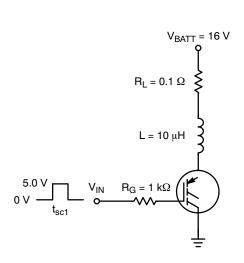


Figure 17. Circuit Configuration for Short Circuit Test #1

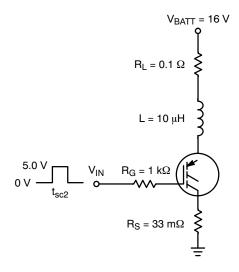


Figure 18. Circuit Configuration for Short Circuit Test #2

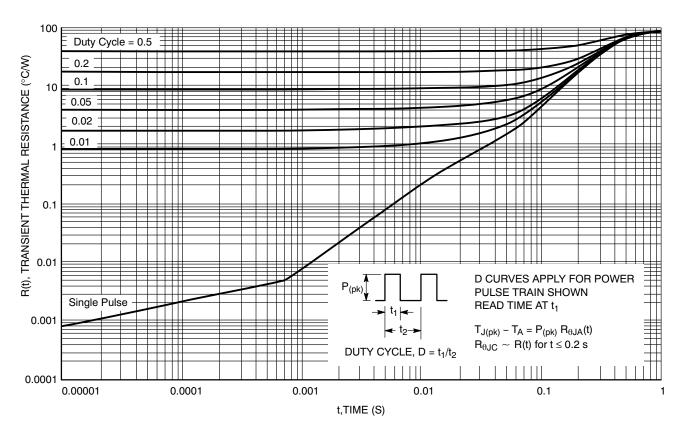
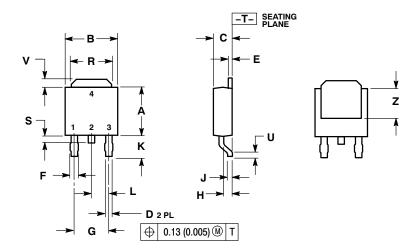


Figure 19. Transient Thermal Resistance (Non-normalized Junction-to-Ambient mounted on minimum pad area)

PACKAGE DIMENSIONS

DPAK CASE 369C ISSUE C



NOTES:

- DIMENSIONING AND TOLERANCING
 PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.

	INC	HES	MILLIMETERS				
DIM	MIN	MAX	MIN	MAX			
Α	0.235	0.245	5.97	6.22			
В	0.250	0.265	6.35	6.73			
C	0.086	0.094	2.19	2.38			
D	0.027	0.035	0.69	0.88			
Е	0.018	0.023	0.46	0.58			
F	0.037	0.045	0.94	1.14			
G	0.180	0.180 BSC		BSC			
Н	0.034	0.040	0.87	1.01			
Ĺ	0.018	0.023	0.46	0.58			
K	0.102	0.114	2.60	2.89			
L	0.090	BSC	2.29	BSC			
R	0.180	0.215	4.57	5.45			
s	0.025	0.040	0.63	1.01			
U	0.020		0.51				
٧	0.035	0.050	0.89	1.27			
Z	0.155		3.93				

STYLE 7:

PIN 1. GATE 2. COLLECTOR 3. EMITTER

COLLECTOR

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body or other applications thered the surgical implant into the polar confidence that the science of the science in which the failure of the SCILLC product could create a situation where surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA **Phone**: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative